

# Product Document



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Premstätten, June 1, 2018

### **PCN13-2018 (New Wafer Sort Test Facility)**

Dear Customer,

ams AG is pleased to inform you that a New Wafer Sort Test Facility has been opened in Asia. It is located in Tampines, Singapore and will enable us to support the ever increasing demand in today's dynamic market environment.

Our business address is:

*ams Sensors Asia Pte. Ltd. (Singapore Tampines)*

JTC Nanopace

11 Tampines Industrial Crescent

Singapore 528606

This new test site is not only intended to increase the electrical testing capacity of ams AG but will also show a positive effect in the supply chain management of the products.

**Bankverbindungen/  
Bankaccounts**  
UniCredit Bank Austria AG, Graz

**IBAN EUR** AT28 1200 0763 1316 1100  
**BIC** BKAUATWW  
**IBAN USD** AT60 1200 0763 1316 1106

**BIC** BKAUATWW  
**Firmenbuchgericht** Graz  
**Firmenbuch Nr.** FN 34109k

**DVR** 0420352  
**UID/VAT** ATU 28560205



### **Other Advantages:**

The new test facility is also strategically situated near to ams AG's key assembly partners in Asia, both in wafer fabrication and manufacturing.

Key Partners Located in Asia

- a) TSMC (Taiwan)
- b) Amkor (Philippines and Korea)
- c) ASE (Taiwan and Korea)
- d) AIT (Indonesia)
- e) Carsem (Malaysia)

### **Strategy:**

1. Teams of test and quality experts were formed at ams AG (Austria) that will support, provide comprehensive trainings and be counterparts of the start-up team in Singapore.
2. The test equipment (e.g. probers) will all be identical to ams AG (Austria).
3. Specifications, product and process controls, trip limits, cut-off limits, acceptance criteria, including product packaging will be applied and implemented to all the products that will be tested in this new ams AG test site and will all be identical to ams AG (Austria).
4. Same specific device document (such as C-spec) will be used by ams *Sensors Asia Pte. Ltd.* (Singapore) except for the change in the test site information.

### **Impact on Product:**

No impact on product is anticipated as there will be no changes in terms of form, fit and function.



**Process Flow Matrix:**

<b>Process Flow</b>	<b>Old Test Site</b>	<b>New Test Site</b>
Wafer Fabrication	ams AG Austria	ams AG Austria
Sort	ams AG Austria	ams AG Austria or <i>ams Sensors Asia Pte. Ltd. Singapore</i>
Assembly	Amkor Philippines	Amko Philippines
Rre Burnin Test	ams Austria or ams Philippines	ams Austria or ams Philippines
Burnin	SEMPAC	SEMPAC
Final Test	ams Austria or ams Philippines	ams Austria or ams Philippines
Tape & Reel	ams Philippines	ams Philippines
Delivery	ams Philippines	ams Philippines



Product(s) affected:

material ID	description
187760009	AS5132-HSST SSOP20 LF T&RDP
187760014	AS5132-HSSM SSOP20 LF T&RDP

Detailed activities and an actual status of this project are available upon request.

If you do have further questions, please do not hesitate to contact me.

Please be advised that unless we receive your written refusal concerning this PCN within 30 days, the PCN shall be deemed accepted.

Best regards,

A handwritten signature in black ink, appearing to read 'D. Gleispach'.

Dietmar Gleispach

ams AG

Director Operations EAS